TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSIII)

2SK2968

DC-DC Converter, Relay Drive and Motor Drive Applications

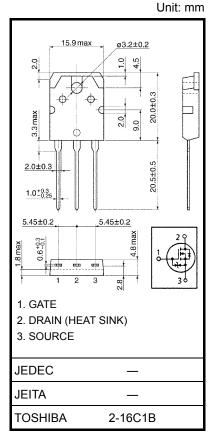
• Low drain-source ON resistance : RDS (ON) = 1.05Ω (typ.) • High forward transfer admittance : $|Y_{fs}| = 7.6 S$ (typ.)

• Low leakage current $: I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 720 \text{ V)}$

• Enhancement mode $: V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

Absolute Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	900	V	
Drain-gate voltage (Ro	_{SS} = 20 kΩ)	V_{DGR}	900	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	10	Α	
Diam current	Pulse (Note 1)	I _{DP}	30	Α	
Drain power dissipation	n (Tc = 25°C)	P_{D}	150	W	
Single pulse avalanche energy (Note 2)		E _{AS}	810	mJ	
Avalanche current		I _{AR}	10	Α	
Repetitive avalanche e	nergy (Note 3)	E _{AR}	15	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	ange	T _{stg}	-55~150	°C	



Weight: 4.6 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	0.833	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	50	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 14.9 mH, R_G = 25 Ω , I_{AR} = 10 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.



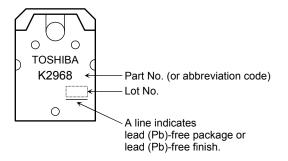
Electrical Characteristics (Ta = 25°C)

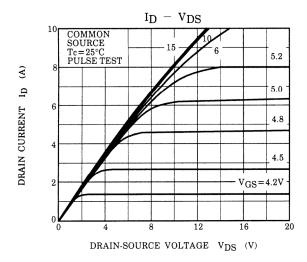
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	irrent	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V		_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	900	_	_	V
Gate threshold v	oltage/	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 4 A	_	1.05	1.25	Ω
Forward transfer	r admittance	Y _{fs}	V _{DS} = 15 V, I _D = 4 A	3.5	7.6	_	S
Input capacitano	e	C _{iss}		_	2150	_	
Reverse transfe	r capacitance	C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	35	_	pF
Output capacitance		Coss			220	_	
Switching time	Rise time	t _r	V_{GS} V_{OUT} V_{OUT} V_{DD} V_{OUT} V_{DD}	_	25	_	
	Turn-on time	t _{on}		_	60	_	ne
	Fall time	t _f		_	25	_	ns
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\mathbf{W}} = 10 \mu s$	_	120	_	
Total gate charge (gate-source plus gate-drain)		Qg	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 10 A		70		
Gate-source charge		Q _{gs}			37	_	nC
Gate-drain ("miller") Charge		Q_{gd}			33	_	

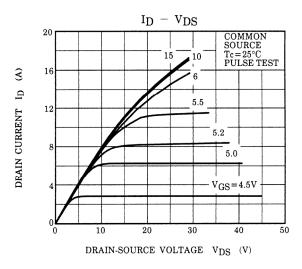
Source-Drain Ratings and Characteristics (Ta = 25°C)

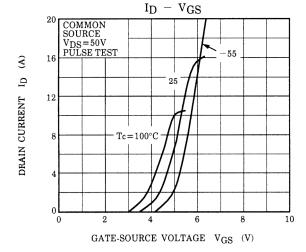
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	10	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	30	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 10 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	t _{rr}	I _{DR} = 10 A, V _{GS} = 0 V	1	1300	1	ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 A / μs		14.5	_	μC

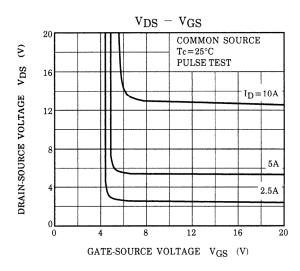
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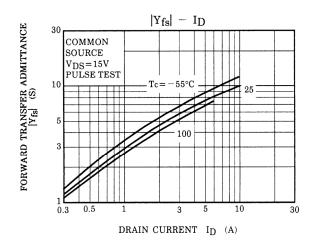


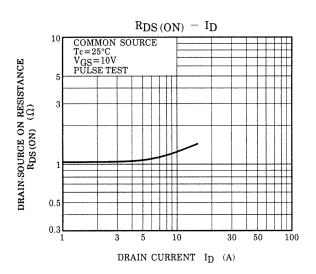




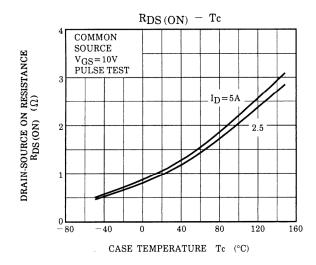


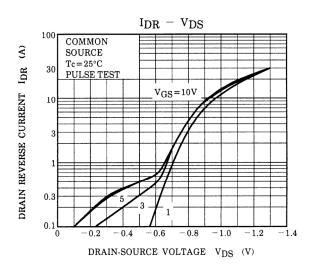


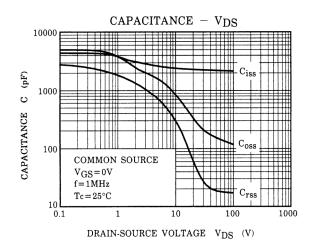


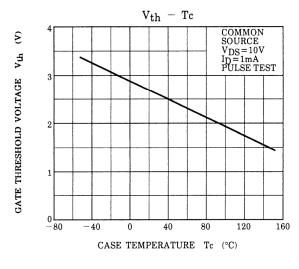


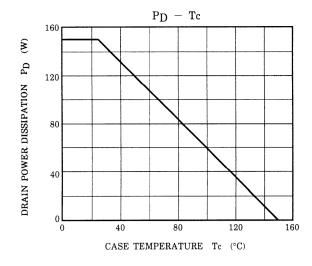
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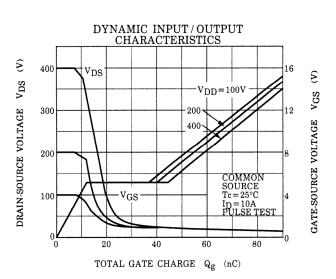


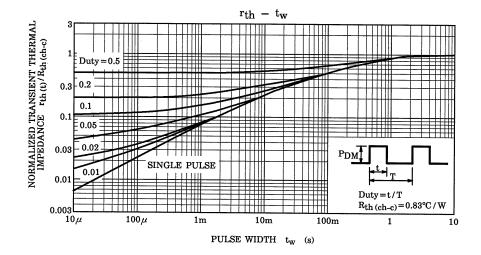


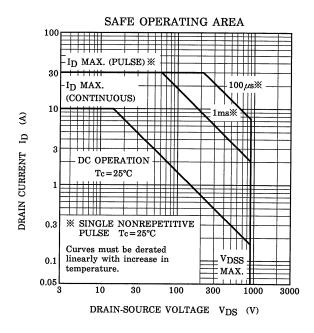


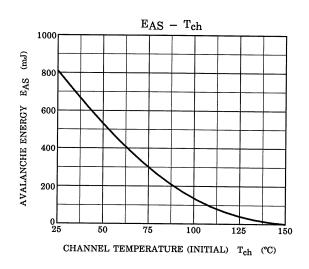


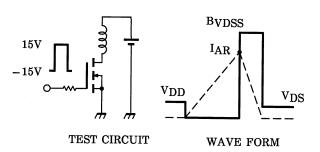












$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 90~V,~L = 14.9~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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